#### **REMARKS**

#### Rejection Under 35 U.S.C. § 112, second paragraph:

The Patent Office has rejected claims 1-13 under § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter that the Applicant regards as the invention. In response to this rejection, claims 1 and 8 have been amended, removing the phrase "articles such as". Claim 11 has been amended to more clearly reflect the spatial relationship between the adhesive strip and the non-functional film layer. The Applicant hereby submits that the foregoing amendments are sufficient to overcome the stated rejections.

## Rejection Under 35 U.S.C. § 102(e):

The Patent Office has rejected claims 1-13 under § 102(e) as being anticipated by Weekes et al., U.S. Patent Application 2004/0253473. As noted by the Patent Office in the present action, Weekes specifically "teaches a laminate comprising an aluminum non-functional layer overlaid on both sides with copper conductive layers of greater lateral scope and [the copper layers are] joined together at the periphery."

Both claims 1 and 8 recite language that specifies that the non-functional layer be joined to the functional layer. Weekes does not teach this limitation, but in fact teaches away from it. In particular, Weekes teaches that the "[f]oils 12, 14 surround carrier 16 but are otherwise not attached to it." As such, the structure disclosed in Weekes does not disclose or teach every limitation as recited, and thus does not anticipate the invention recited in claims 1 and 8. The Applicant hereby submits that amended claims 1 and 8, and those claims that depend there from, are novel in view of Weekes.

## Rejections Under 35 U.S.C. § 102(b):

The Patent Office has rejected claims 1-3, 5-8 and 10-13 under § 102(b) as being anticipated by U.S. Patent No. 5,725,937 to Johnston. Unlike Weekes et al., discussed above, Johnston does contemplate the mating of a single sheet of copper to a single sheet of aluminum. However, Johnston does not disclose in the specification or any figures, an embodiment of such a device in which one layer is greater in lateral dimension than the other.

On the contrary, Figure 5 of the Johnston patent specifically illustrates that the C portion and the A portion of the component are overlapped with precision, as further indicated by the exacting placement of the adhesive (40).

This reading of the Johnston reference is further buttressed by the introduction by Johnston of the so-called islands (50), which serve to "seal the clean interface between the copper C<sub>i</sub> and the aluminum A<sub>i</sub> from the bleeding of the melted prepeg during the heating and bonding process." Col. 7, lines 37-40. The introduction of this element into the Johnston configuration is contrary to the teachings and intended claim scope of the present invention.

As indicated in the specification of the present invention, the larger of the two film layers defines a flashing area 24, the purpose of which is also to catch the flowing resin during the lamination process. In short, the purpose of the flashing area 24 is the same as that of Johnston's islands, but the two means for absorbing flowing resin are not identical and indeed teach away from each other. As such, the Applicant respectfully suggests that Johnston does not in fact teach that one of a conductive and non-functional film layer has larger lateral dimensions as compared to the other. Given the foregoing, it is submitted that amended claims 1 and 8 are novel and patentable in view of Johnston.

The Patent Office further rejected claims 1, 5 and 6 under § 102(b) as being anticipated by Steiner et al., U.S. Patent Application 2002/0061415. Like Weekes and Johnston, however, Steiner fails to disclose a single conductive film layer joined to a single non-functional film layer in such a manner that one of the layers has larger lateral dimensions than the other, as recited in claims 1 and 8. Each of Figures 1, 3 and 5 of Steiner specifically disclose an aluminum substrate (24) having two copper layers (22) of equal lateral dimension disposed thereon. To the extent that Steiner discloses any layer having a different lateral dimension, it is the resin (26), which is an element not claimed in the present application. Accordingly, given the foregoing amendments and arguments presented above, it is respectfully submitted that amended claims 1 and 8 are novel and patentable in view of Steiner.

# Rejection Under 35 U.S.C. § 103(a):

The Patent Office has rejected claims 2, 3 and 8-13 under § 103(a) as being unpatentable over Weekes. The Applicant hereby restates the foregoing arguments, and notes again that Weekes specifically teaches that its Al and Cu layers are not joined or bonded together in any fashion, contrary to the recitations of the rejected claims. Therefore, it is respectfully submitted that Weekes teaches away from the limitations of the present invention,

which is necessarily the case as Weekes employs three layers in a sandwich format as opposed

to the two-layer component described and claimed in the present invention. As amended claims

1 and 8 are both novel and non-obvious in view of Weekes, it is respectfully submitted that each

claim that depends there from is also in condition for allowance as Weekes fails to teach,

suggest or motivate any of the combinations or limitations of the independent claims.

**Newly Submitted Claims:** 

Claims 18-30 have been added to more particularly point out and distinctly claim the

structural features of the present invention. Independent claim 18 recites in part that the

adhesive defines a central area and a flashing area, the latter of which is not known in the prior

art. As noted and argued above, the only other reference that teaches a means or mechanism

for receiving flowing resin from the prepage is Johnston, and in that case the invention employs

the so-called islands of adhesive to do so. The present invention as claimed in claim 18 utilizes

a portion of the conductive film layer itself, and is therefore readily distinguishable over

Johnston. Moreover, the Applicant submits that the present invention provides a structure for

receiving flowing resin that is more economical, easier to construct and more reliable than any

other taught or suggested by the prior art. For these reasons and those cited above, the

Applicant respectfully submits that claims 18-30 are also in condition for allowance.

Summary

In light of the above amendment, consideration of the subject patent application is

respectfully requested.

Respectfully submitted,

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